

ABSTRACT

The present invention provides a substrate processing method, comprising: measuring characteristic parameter of a liquid film on the surface of a pre-wetted substrate to generate the second characteristic data; acquiring the first characteristic data as comparison data, comparing the second characteristic data with the comparison data to determine whether a pre-wetting result of the substrate is qualified. If an error between the first characteristic data and the second characteristic data is greater than a preset value, determining that the pre-wetting result of the substrate is unqualified; if the error between the first characteristic data and the second characteristic data is less than or equal to the preset value, determining that the pre-wetting result of the substrate is qualified. According to the pre-wetting result, the next treatment process of the substrate is controlled. The present invention can determine the pre-wetting result of the substrate more efficiently and accurately, and avoid the problem that the liquid film on the substrate is uneven after the pre-wetting of the substrate and the voids are formed in the TSV vias of the substrate after electroplating. At the same time, when the pre-wetting result of the same substrate is unsatisfactory repeatedly, a worker can be reminded to check the fault of a machine to ensure safe production.